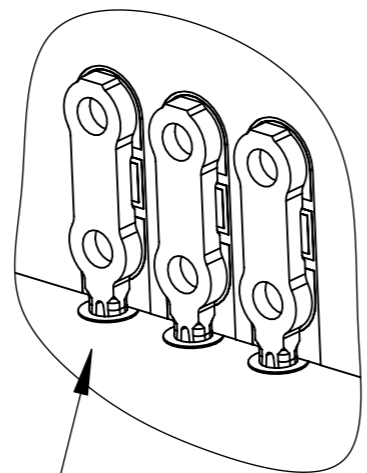
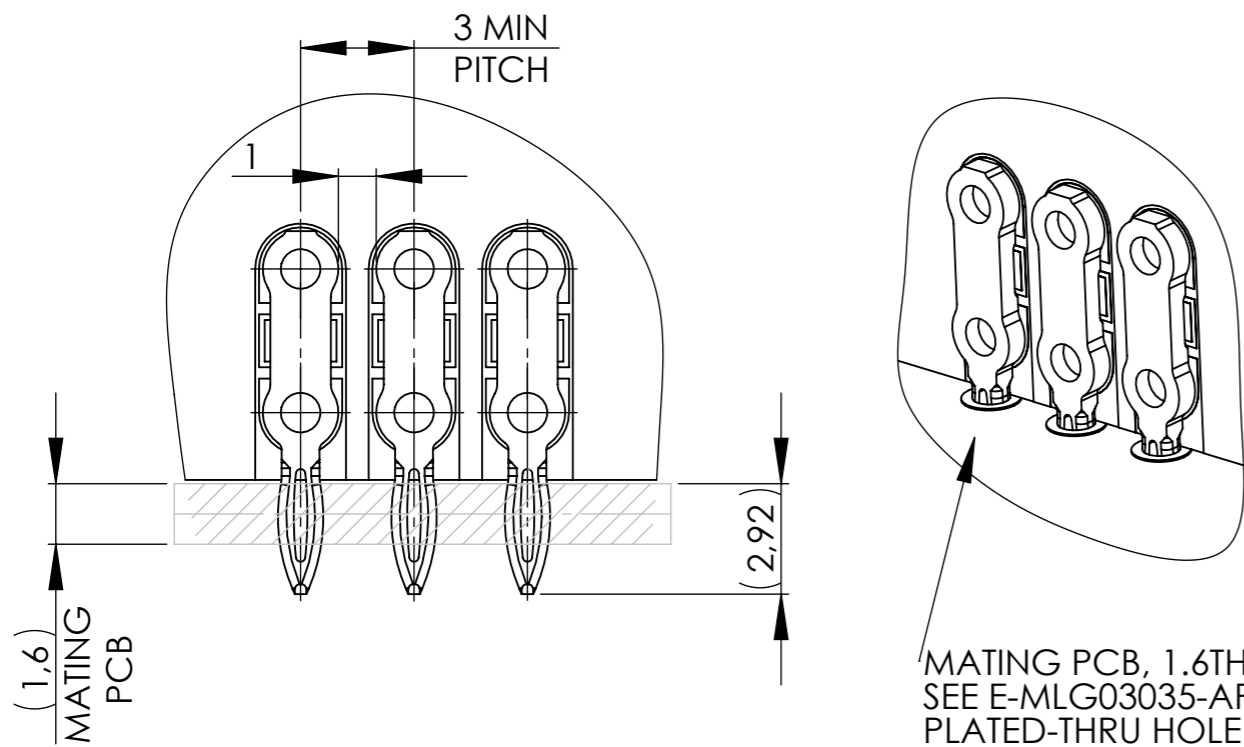
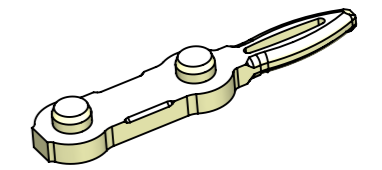


PART STATUS	VALIDATION
PRESS FIT	INTERPLEX 0,64 EON
DRAWING	E-MLG 03035-APP
MATERIAL	C19010 R580
FINISH	POST-PLATED
UNDERPLATE	1.5 - 3.0 Ni
ADHESION TEST ACC. TO ASTM-B-571/11	PEEL OFF
MISSING DIMENSION ACC. TO CAD-MODEL	



PRELIMINARY

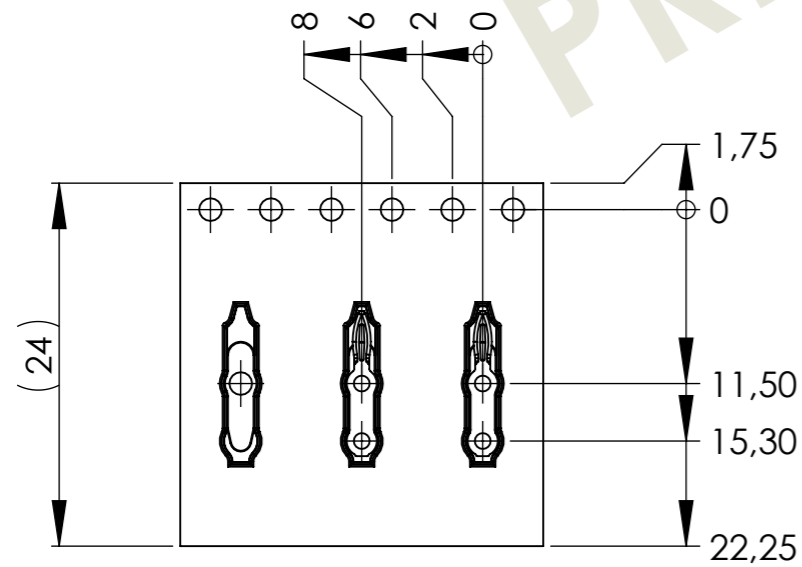
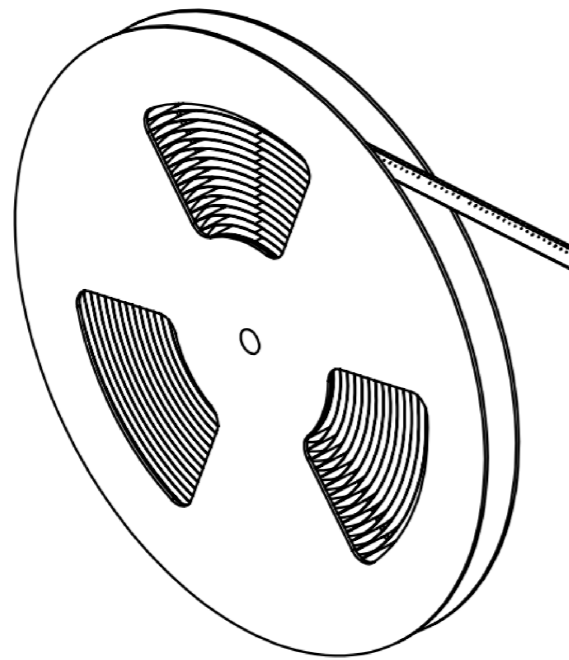


ENNOVI™		ISO- STANDARD (mm)	Vers.	
GEN. TOL.		DIN 2768 mK	Change	Date Name
CHECK DIM.		SCALE 5:1		
MATERIAL		SEE NOTES		FINISH
TITLE		0.64 SMT PRESS FIT HP STRAIGHT		A3
DWG. NO.		E-IPX22002-1		SHEET 1
VOL mm³		WT g		2 SH
SolidWorks				

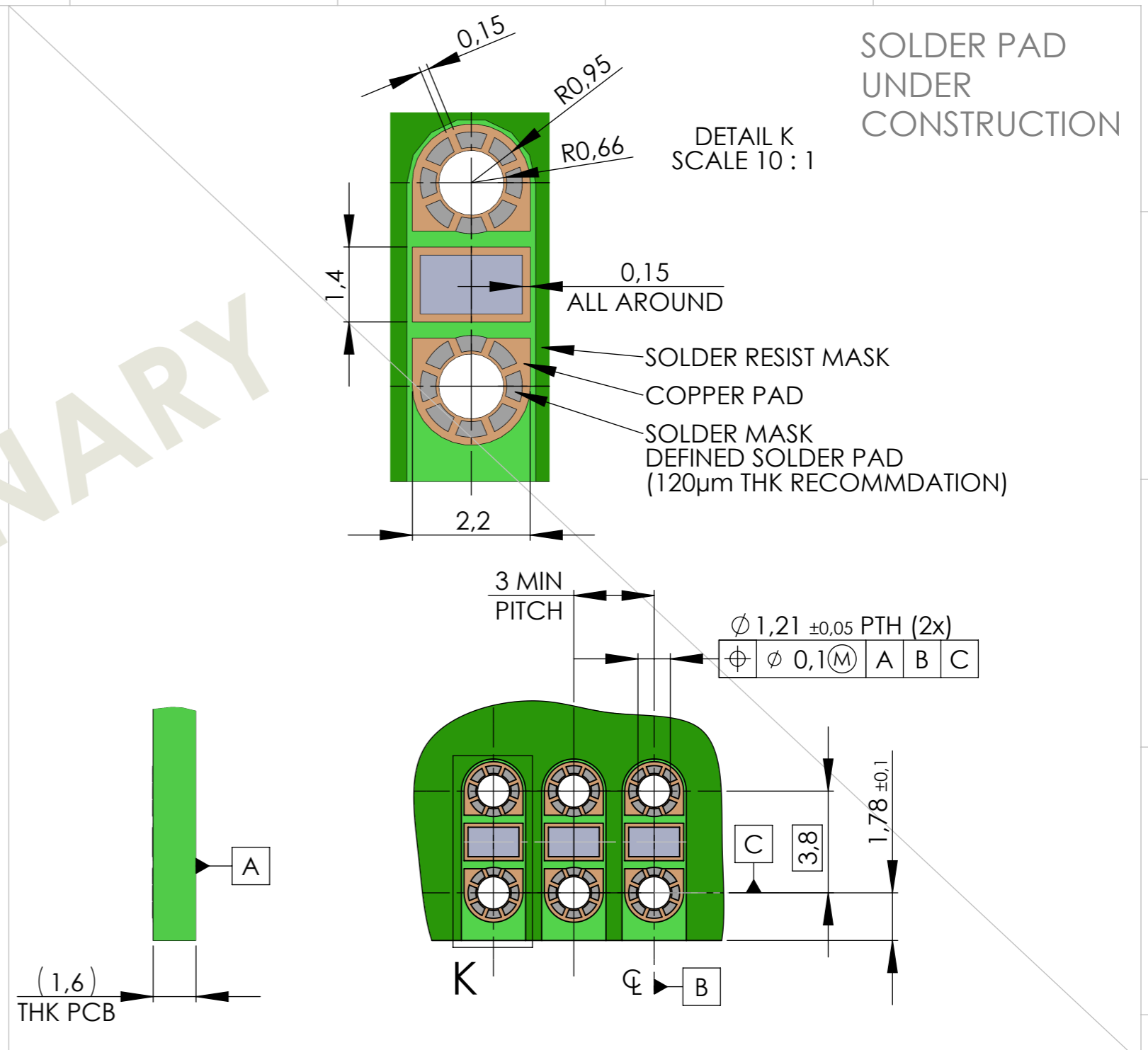
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DATE	NAME
DRAWN 11.01.22	H.J.Hahn
CHECKED 11.01.22	M.Meckl

C	ASSEMBLY ADDED	20.01.23	HJH
B	SOLDER PAD MOD.	02.06.22	HJH
A	SAMPLE (CUSTOMER DRW)	11.01.22	HJH



UNDER CONSTRUCTION



SOLDER PAD UNDER CONSTRUCTION

DETAIL K SCALE 10:1

SOLDER RESIST MASK
COPPER PAD
SOLDER MASK DEFINED SOLDER PAD (120µm THK RECOMMDDATION)

3 MIN PITCH
 $\phi 1,21 \pm 0,05$ PTH (2x)
 $\phi 0,1$ (M) A B C

(1,6) THK PCB

C	ASSEMBLY ADDED	20.01.23	HJH
B	SOLDER PAD MOD.	02.06.22	HJH
A	SAMPLE (CUSTOMER DRW)	11.01.22	HJH
Vers.	Change	Date	Name

ENNOVITM

ISO- STANDARD (mm)

GEN. TOL.

DIN 2768 mK

CHECK DIM.

PROPRIETARY & CONFIDENTIAL

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DATE	NAME
DRAWN 11.01.22	H.J.Hahn
CHECKED 11.01.22	M.Meckl

METRIC

SolidWorks

SCALE 5:1

MATERIAL SEE NOTES

FINISH SEE NOTES

TITLE

0.64 SMT PRESS FIT HP STRAIGHT

DWG. NO.

E-IPX22002-1

A3

SHEET 2
2 SH

VOL

WT